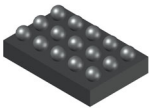
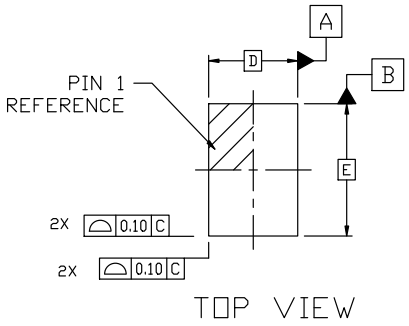
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

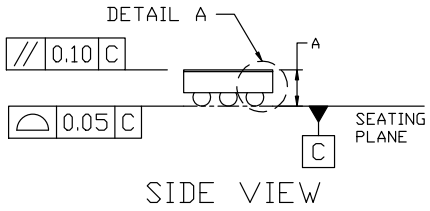


WLCSP15, 1.34x1.99x0.548
CASE 567GB
ISSUE D

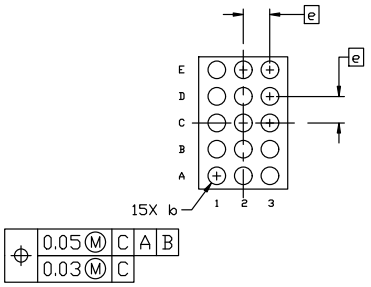
DATE 02 JUN 2022



TOP VIEW



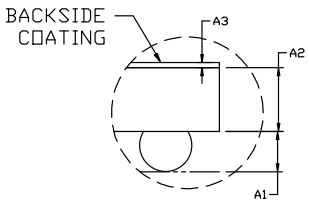
SIDE VIEW



BOTTOM VIEW

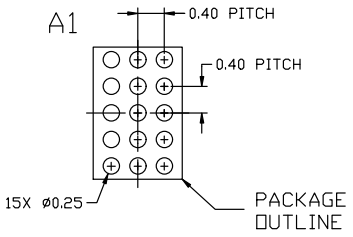
NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION b IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.
4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



DETAIL A
SCALE 1:3

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.498	0.548	0.598
A1	0.178	0.203	0.228
A2	0.295	0.320	0.345
A3	0.025 BSC		
b	0.233	0.263	0.293
D	1.34 BSC		
E	1.99 BSC		
e	0.40 BSC		



RECOMMENDED
MOUNTING FOOTPRINT*

* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*

A = Assembly Location
L = Wafer Lot
Y = Year
W = Work Week
▪ = Pb−Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “▪”, may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	**WLCSP15, 1.34X1.99x0.548**	**PAGE 1 OF 1**

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